



JCT625E 25A SCR

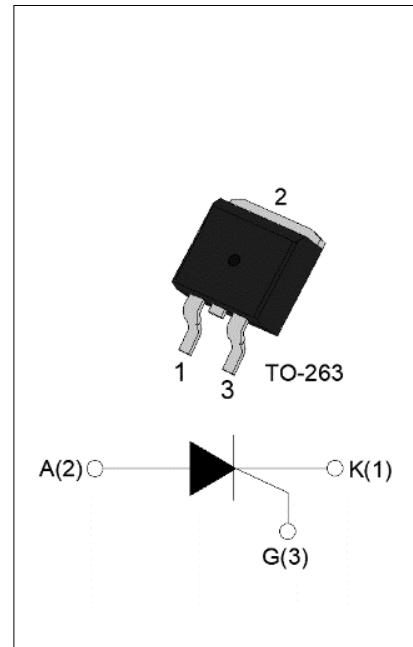
Rev.A.1.0

DESCRIPTION:

With high ability to withstand the shock loading of large current, JCT625E SCR provides high dV/dt rate with strong resistance to electromagnetic interference. It is especially recommended for use on solid state relay, motorcycle, power charger, T-tools etc. Package TO-263 is RoHS compliant.

MAIN FEATURES

Symbol	Value	Unit
$I_{T(RMS)}$	25	A
V_{DRM}/V_{RRM}	600	V
I_{GT}	≤ 20	mA



ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Storage junction temperature range	T_{stg}	-40-150	°C
Operating junction temperature range	T_j	-40-125	°C
Repetitive peak off-state voltage ($T_j=25^\circ\text{C}$)	V_{DRM}	600	V
Repetitive peak reverse voltage ($T_j=25^\circ\text{C}$)	V_{RRM}	600	V
Average on-state current ($T_c \leq 93^\circ\text{C}$)	$I_{T(AV)}$	16	A
RMS on-state current ($T_c \leq 93^\circ\text{C}$)	$I_{T(RMS)}$	25	A
Non repetitive surge peak on-state current ($t_p=10\text{ms}, T_j=25^\circ\text{C}$)	I_{TSM}	320	A
Non repetitive surge peak on-state current ($t_p=8.3\text{ms}, T_j=25^\circ\text{C}$)		352	
I^2t value for fusing ($t_p=10\text{ms}, T_j=25^\circ\text{C}$)	I^2t	512	A^2s
Critical rate of rise of on-state current ($I_G=2 \times I_{GT}, f=100\text{Hz}, T_j=125^\circ\text{C}$)	dI/dt	200	$\text{A}/\mu\text{s}$
Peak gate current ($t_p=20\mu\text{s}, T_j=125^\circ\text{C}$)	I_{GM}	5	A
Average gate power dissipation ($T_j=125^\circ\text{C}$)	$P_{G(AV)}$	1	W

Peak gate power	P_{GM}	20	W
Peak pulse voltage ($T_j=25^\circ C$; non-repetitive, off-state; FIG.8)	V_{PP}	0.5	kV

ELECTRICAL CHARACTERISTICS ($T_j=25^\circ C$ unless otherwise specified)

Symbol	Test Condition	Value			Unit
		MIN.	TYP.	MAX.	
I_{GT}	$V_D=12V R_L=33\Omega$	-	-	20	mA
V_{GT}		-	-	1	V
V_{GD}	$V_D=V_{DRM} T_j=125^\circ C R_L=3.3K\Omega$	0.2	-	-	V
I_L	$I_G=1.2I_{GT}$	-	-	70	mA
I_H	$I_T=500mA$	-	-	60	mA
dV/dt	$V_D=400V$ Gate Open $T_j=125^\circ C$	1200	-	-	V/ μ s
t_{on}	$I_G=20mA I_A=200mA I_R=20mA$ $T_j=25^\circ C$	-	2	-	μ s
t_{off}		-	50	-	

STATIC CHARACTERISTICS

Symbol	Parameter	Value(MAX.)	Unit
V_{TM}	$I_{TM}=50A t_p=380\mu s$	1.5	V
V_{TO}	Threshold voltage	0.72	V
R_D	Dynamic resistance	16	$m\Omega$
I_{DRM}	$V_D=V_{DRM} V_R=V_{RRM}$	5	μA
I_{RRM}		0.5	mA

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	junction to case(DC)	1	$^\circ C/W$
$R_{th(j-a)}$	junction to ambient (DC, in free air, $S=1cm^2$)	45	$^\circ C/W$

ORDERING INFORMATION

J	CT	6	25	E	-/
JieJie Microelectronics Co.,Ltd.					Blank:Tube -TR:Tape & Reel
	SCRs			E:TO-263	
6:V _{DRM} / V _{RRM} ≥600V			I _{T(RMS)} :25A		

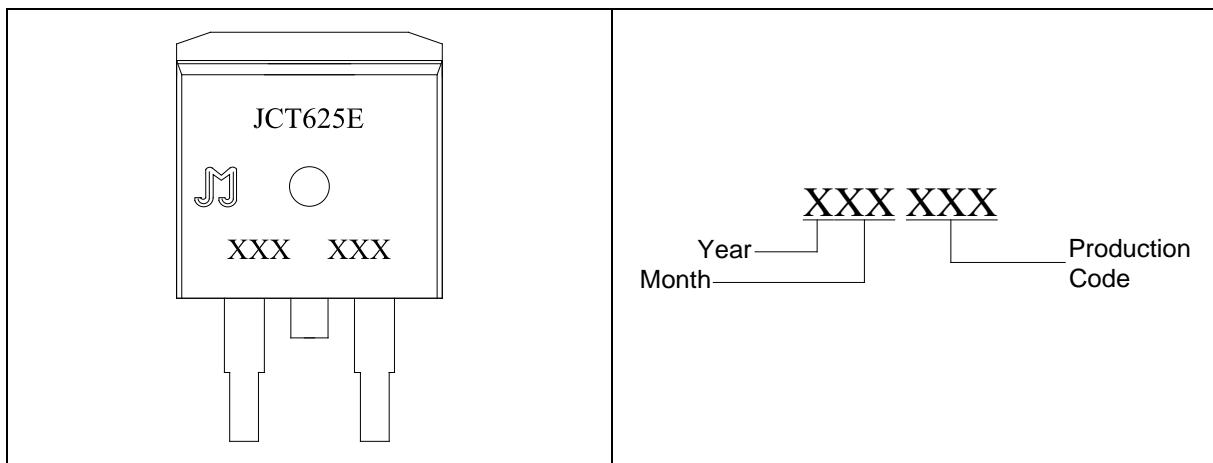
MARKING

FIG.1 Maximum power dissipation versus RMS on-state current

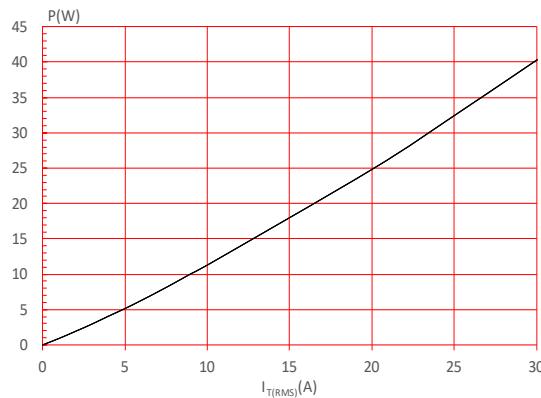


FIG.3: RMS on-state current versus ambient temperature (printed circuit board FR4,copper thickness:35μm)(full cycle)

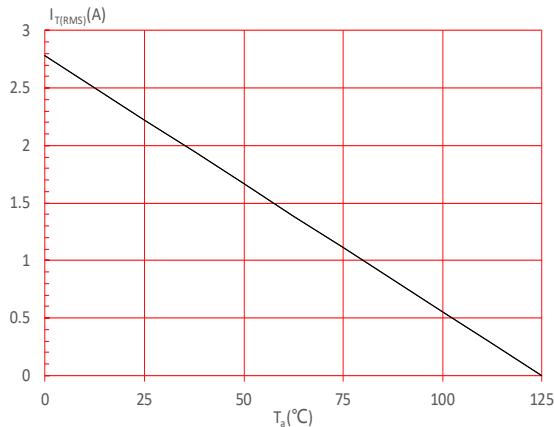


FIG.5: On-state characteristics

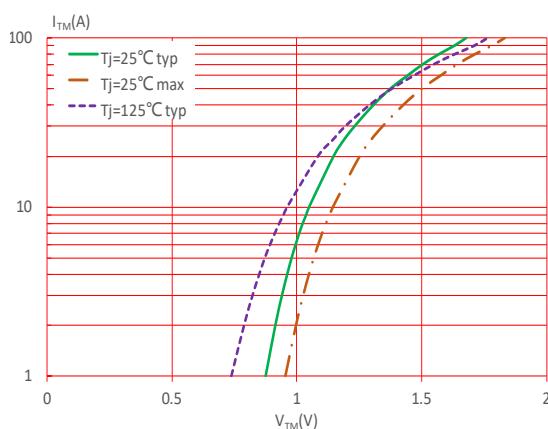


FIG.2: RMS on-state current versus case temperature

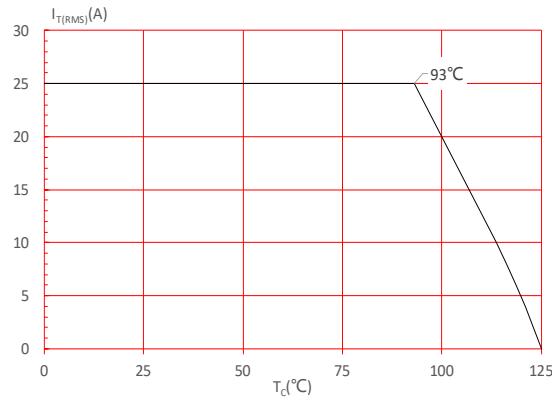


FIG.4: Surge peak on-state current versus number of cycles

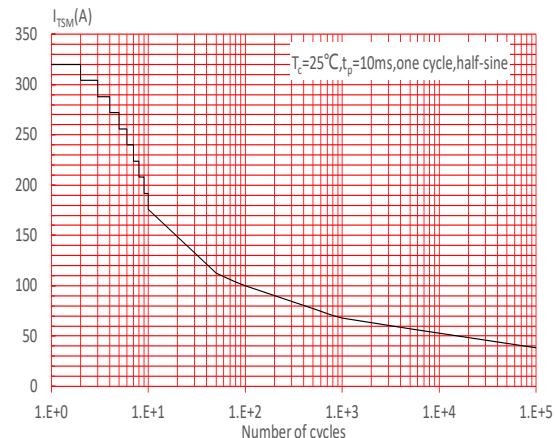


FIG.6: Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 10\text{ms}$, and corresponding value of I^2t ($dI/dt < 200\text{A}/\mu\text{s}$)

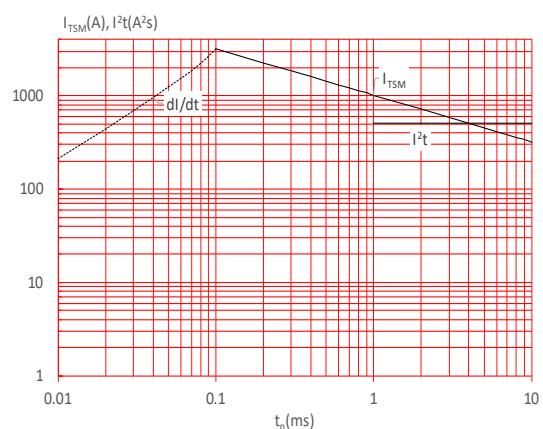


FIG.7: Relative variations of gate trigger current, holding current and latching current versus junction temperature

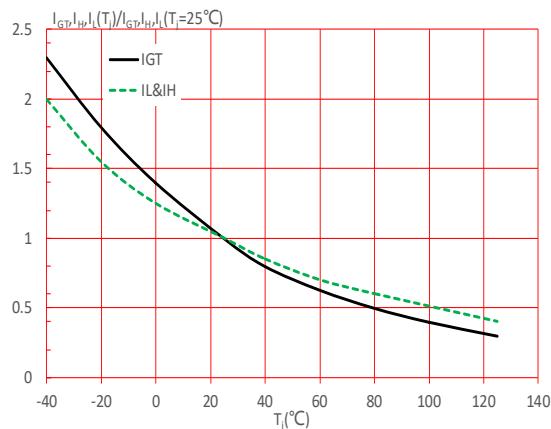
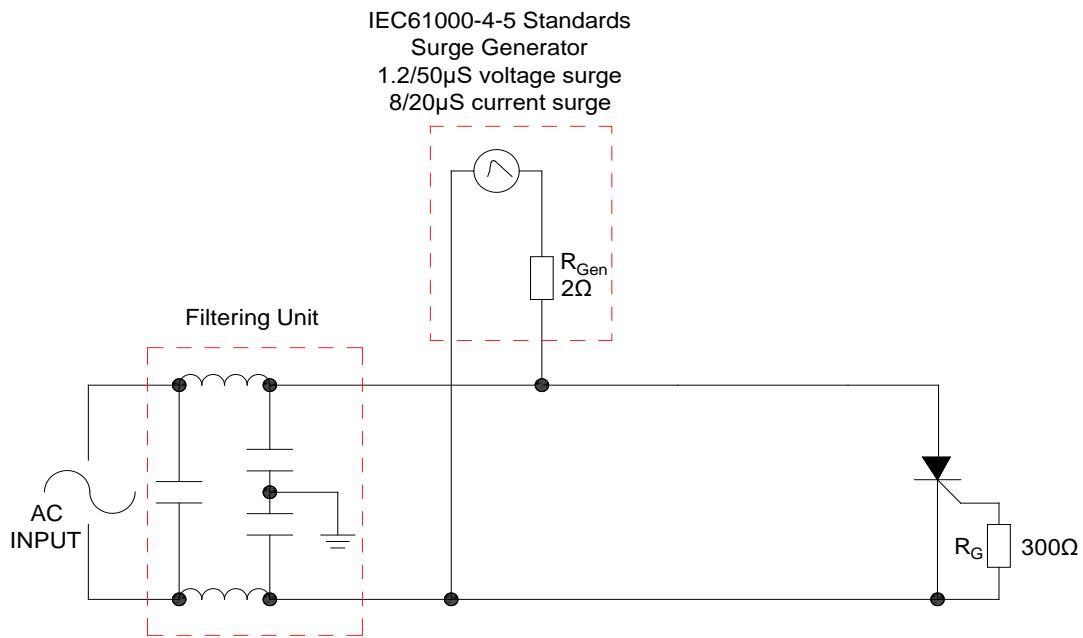
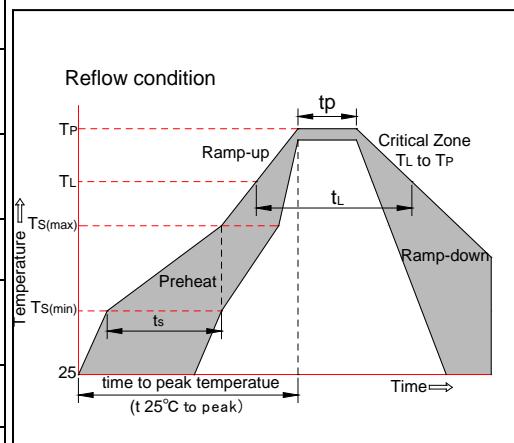


FIG.8: Test circuit for inductive and resistive loads to IEC-61000-4-5 standards.



SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L) (Liquidus)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		20-40secs.
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_p)		8 min. Max
Do not exceed		+260°C



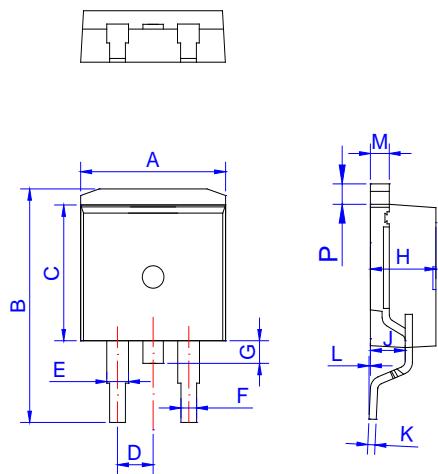
ORDERING INFORMATION

Order code	Voltage V_{DRM}/V_{RRM} (V)	IGT(mA)	Package	Base qty. (pcs)	Delivery mode
JCT625E	600	20	TO-263	50	Tube
JCT625E-TR				800	Tape & Reel

Document Revision History

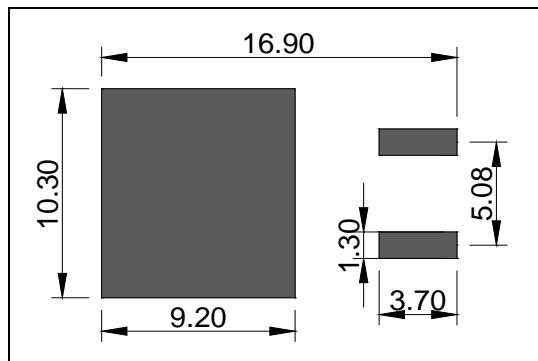
Date	Revision	Changes
Apr.13, 2023	A.1.0	Last update

PACKAGE MECHANICAL DATA

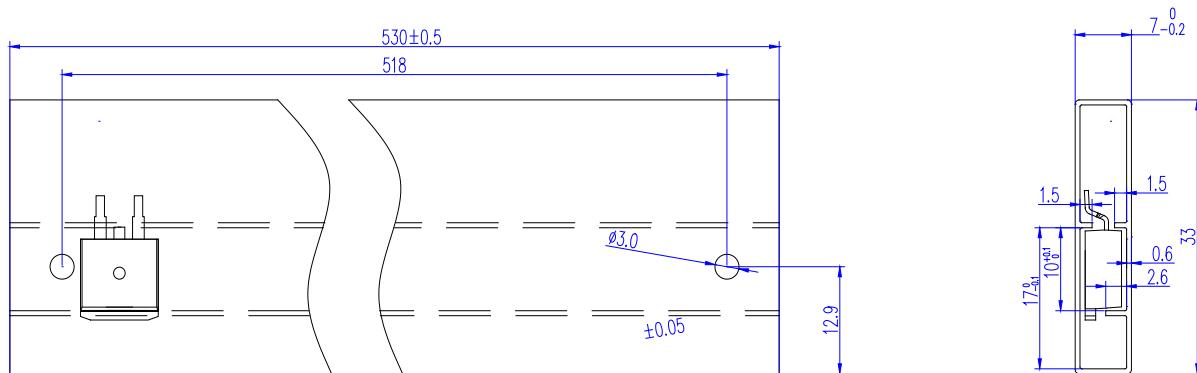


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	9.90		10.20	0.390		0.402
B	14.70		15.80	0.579		0.622
C	9.40		9.60	0.37		0.378
D	2.40		2.70	0.094		0.106
E	1.20		1.50	0.047		0.059
F	0.75		0.85	0.029		0.033
G	1.00		1.50	0.039		0.059
H	4.40		4.70	0.173		0.185
J	2.30		2.70	0.091		0.106
K	0.38		0.55	0.015		0.022
L	0	0.10	0.25	0	0.004	0.010
M	1.25		1.35	0.049		0.053
P	1.20		1.50	0.047		0.059

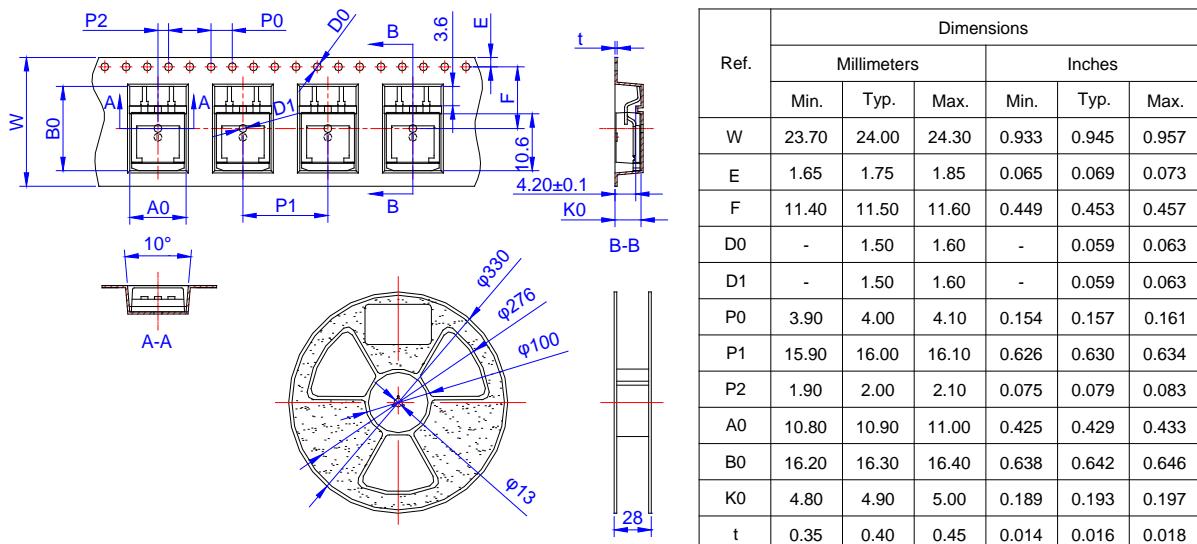
FOOTPRINT-TO-263 (dimensions in mm)



DELIVERY MODE



PACKAGE	OUTLINE	TUBE (PCS)	INNER BOX (PCS)	PER CARTON
TO-263	TUBE	50	1,000	5,000



PACKAGE	OUTLINE	REEL (PCS)	PER CARTON (PCS)	TAPE & REEL
TO-263	TAPING	800	4,000	13 inch

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